

MACHVISION

Investor Conference

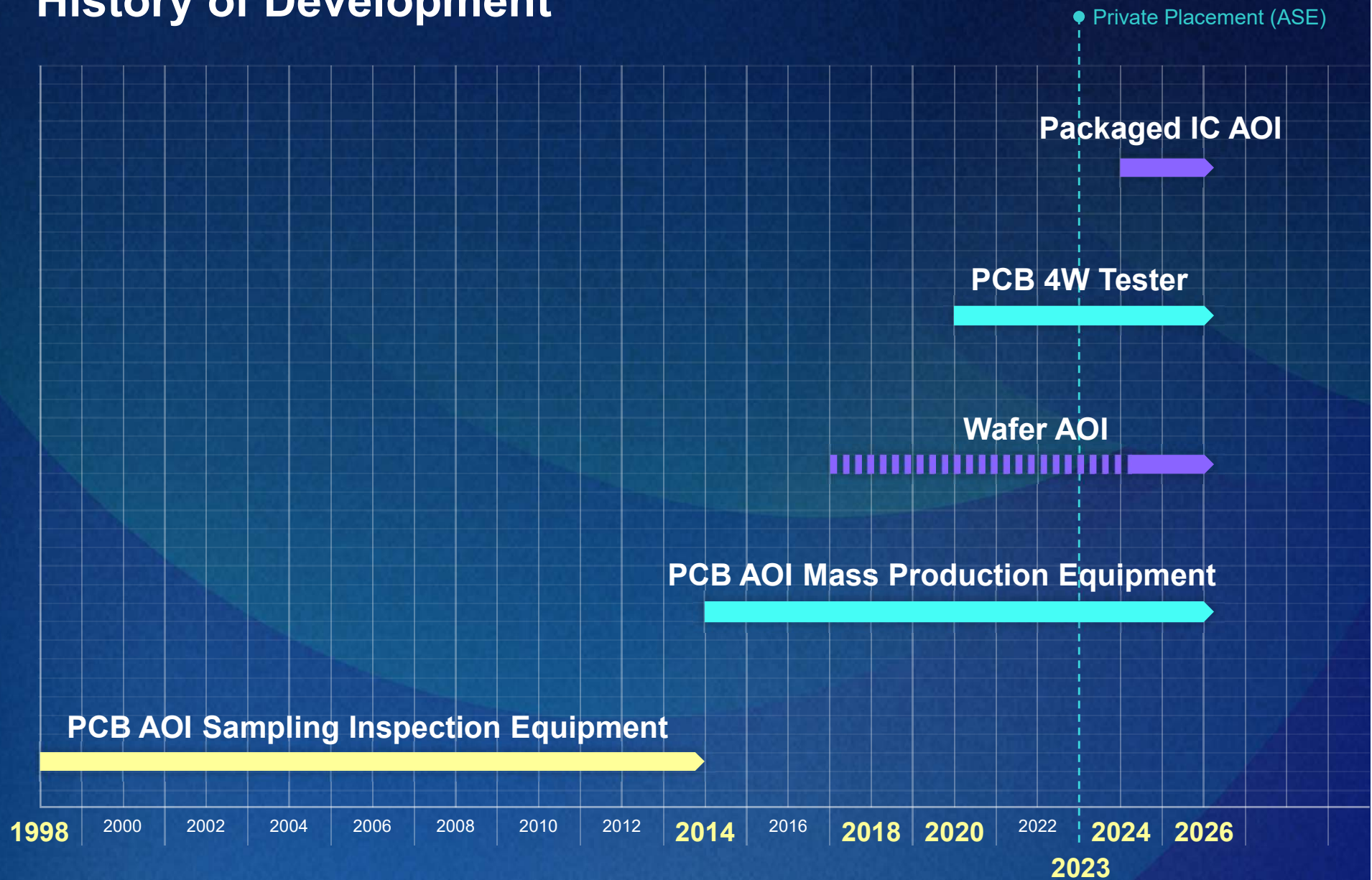
Chairman	Collin Wang
CEO	Jasper Chen
CFO	Evoun Su

Product Development Policy

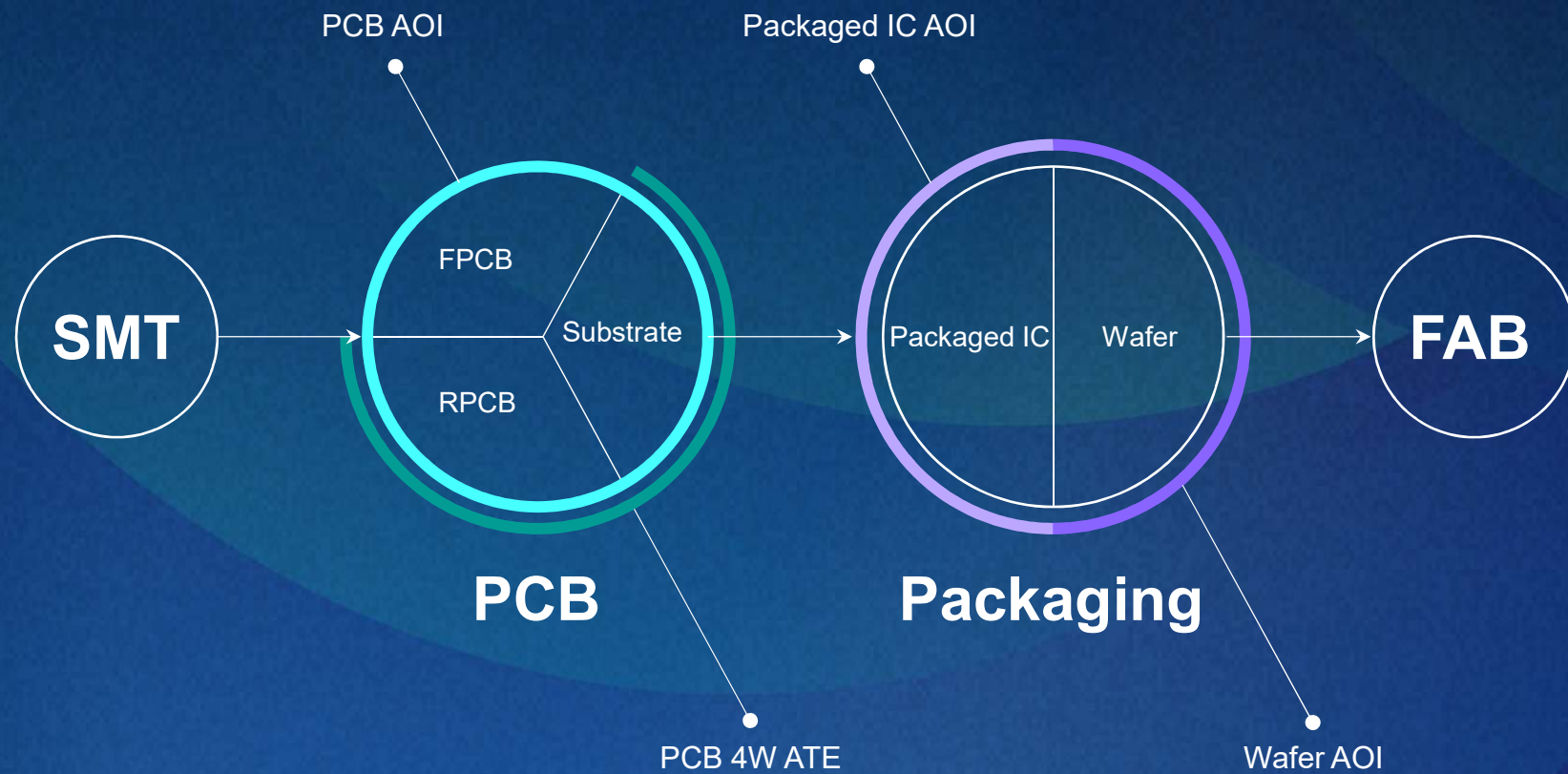
- ▶ **Unique Products.**

- ▶ **Gross Profit Margin of over 60%.**

History of Development



“Dual-track, Four-line” Development Strategy



AI Industry Chain

1

GPU / CPU / HBM

NVIDIA, AMD, TSMC, Intel...

2

Advanced Packaging

TSMC, Samsung, Intel, ASE...

3

**Substrate / High-end PCB /
Server Board**

Unimicron, Nan Ya PCB, Compeq,
Zhen Ding, GCE, WUS...

4

**AI System assembly /
Power supply / Heat dissipation**

Quanta, Wistron, Pegatron, Inventec...

5

Cloud Platform

Microsoft, Google, Amazon...

6

Application Software

Gemini, Chat GPT, Claude, Perplexity...

2025 vs. Present Equipment

2025

PCB AOI (12/2)



PCB

PCB 4W ATE (0/2)

Packaged IC AOI (0/1)



Packaging

Wafer AOI (1/3)

Present Equipment

PCB AOI (14/3)



PCB

PCB 4W ATE (1/3)

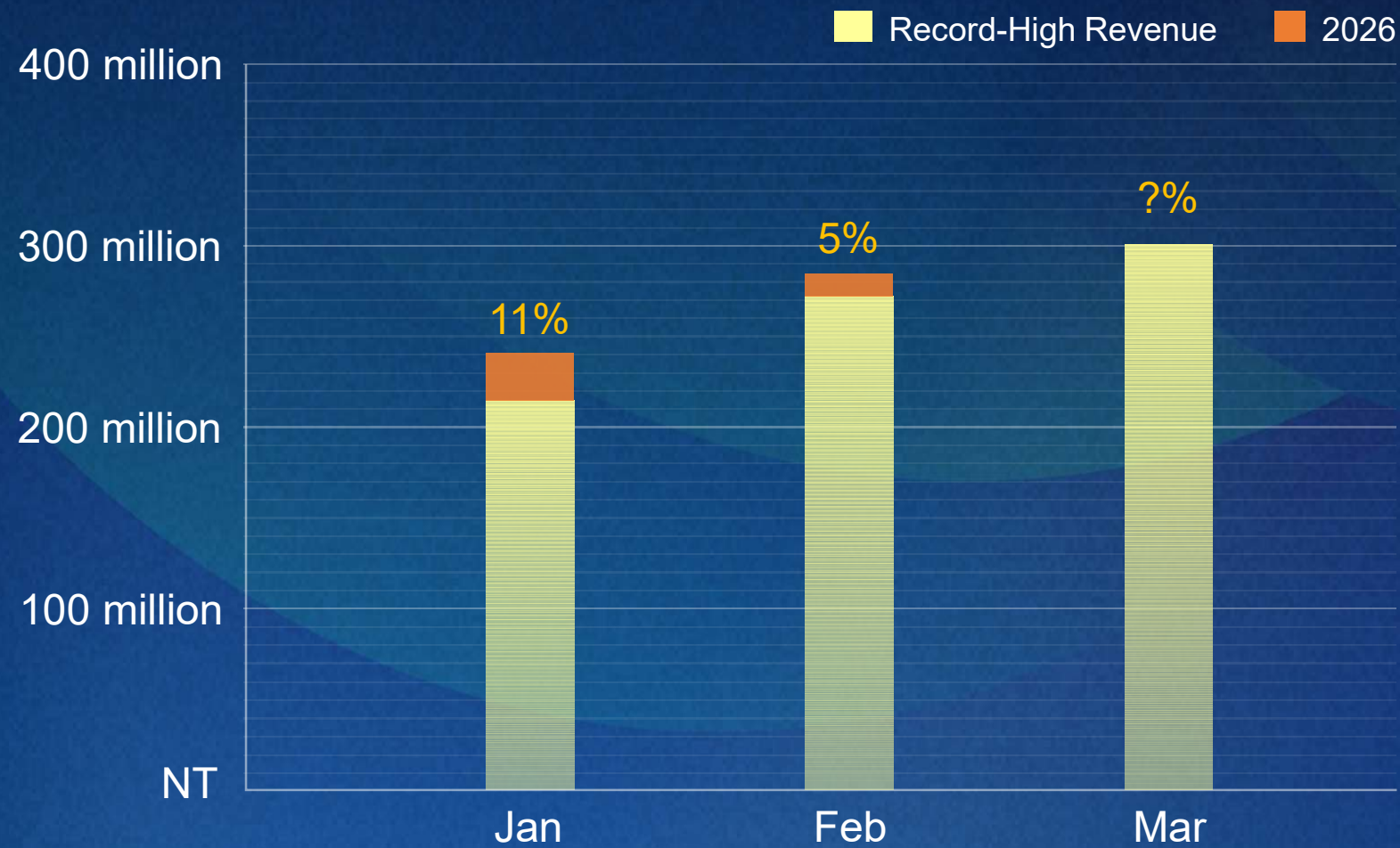
Packaged IC AOI (0/2)



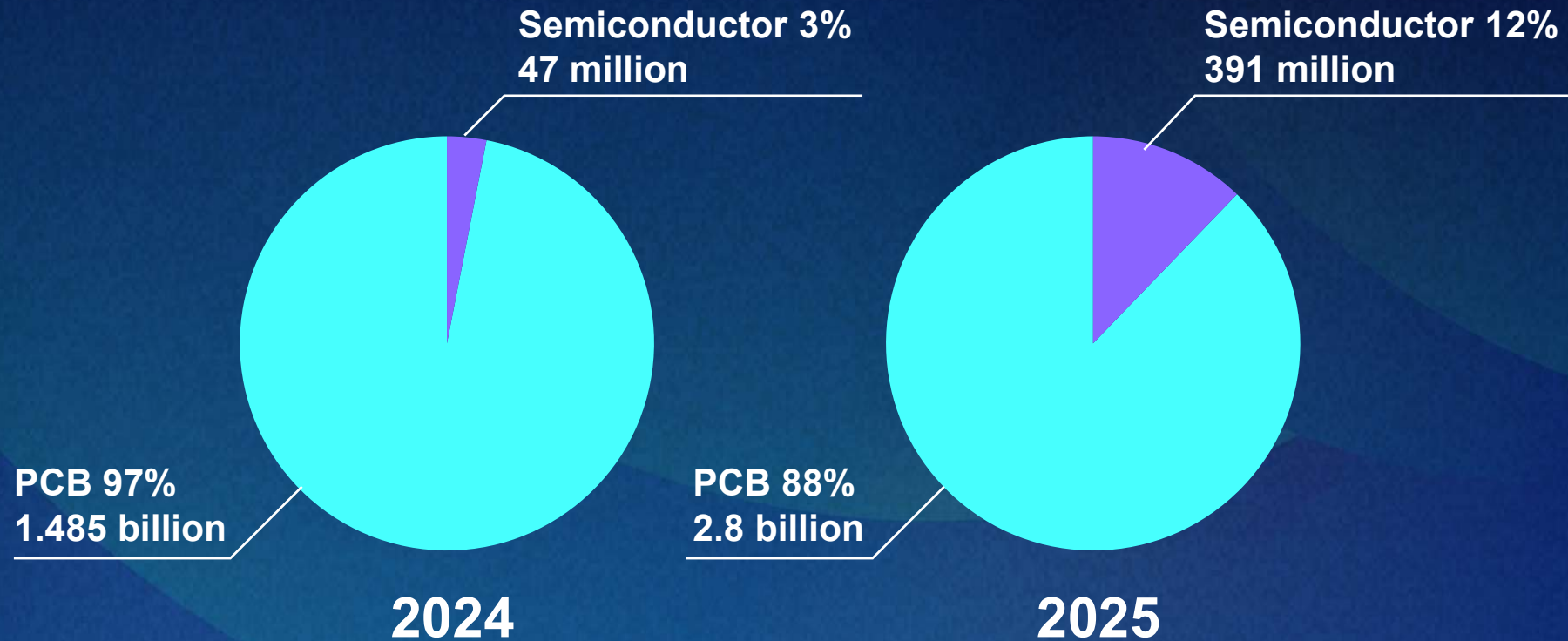
Packaging

Wafer AOI (3/1)

Record-High Revenue vs. 2026 Revenue



2024 vs. 2025 PCB / Semiconductor Revenue



PCB revenue increased **1.88 times**.

Semiconductor revenue increased **8 times**.

2025 vs. Present Equipment

2025

PCB AOI (12/2)



PCB

PCB 4W ATE (0/2)

Packaged IC AOI (0/1)



Packaging

Wafer AOI (1/3)

Present Equipment

PCB AOI (14/3)



PCB

PCB 4W ATE (1/3)

Packaged IC AOI (0/2)



Packaging

Wafer AOI (3/1)

Production Expansion Plan

2026.8 Kunshan



2026.9 HSP Plant 3



2026.10 THAI



Q & A